



HOSTAFORM® LW90EWX

HOSTAFORM®

Hostaform® LW90EWX is a specialty low wear grade of acetal copolymer designed for improved performance including when paired against other thermoplastic resins (PBT, PA, PC, PMMA) or steel. Due to the special wax blend the material has a good weld line strength.

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Froductinionnation			
Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate	9.5	cm ³ /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Typical mechanical properties			
Tensile modulus	2800	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min		MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Nominal strain at break	28	%	ISO 527-1/-2
Charpy impact strength, 23°C	180	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m²	ISO 179/1eA
Ball indentation hardness, H 358/30		MPa	ISO 2039-1
Poisson's ratio	0.37 ^[C]		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa		°C	ISO 75-1/-2
Temperature of deficution under load, 1.0 Mil a	32	0	100 13-1/-2

Physical/Other properties

Density	1400 kg/m ³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100 °(C
Drying Time, Dehumidified Dryer	3-4 h	
Processing Moisture Content	≤0.2 %)
Melt Temperature Optimum	200 °(C
Min. melt temperature	190 °(С
Max. melt temperature	210 °(С
Screw tangential speed	≤0.3 m	/s
Mold Temperature Optimum	100 °(C
Min. mould temperature	80 °C	С
Max. mould temperature	120 °(С
Hold pressure range	60 - 120 M	Pa
Back pressure	4 M	Pa

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Revised: 2024-07-17 Source: Celanese Materials Database





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Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent

Special characteristics Low wear / Low friction

Additional information

Processing Notes Storage

The product can then be stored in standard conditions until processed.

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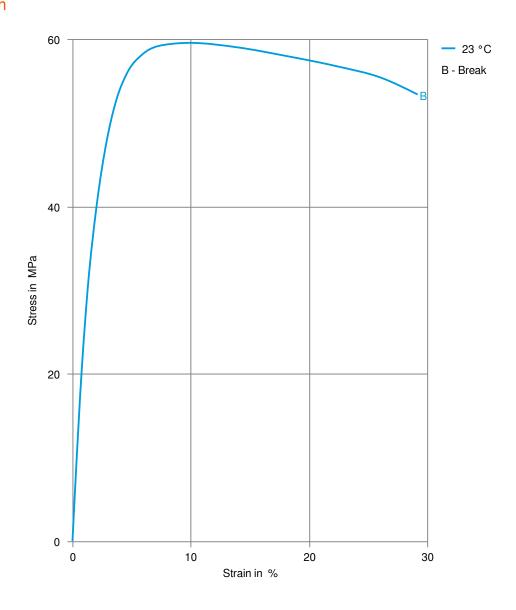




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Stress-strain



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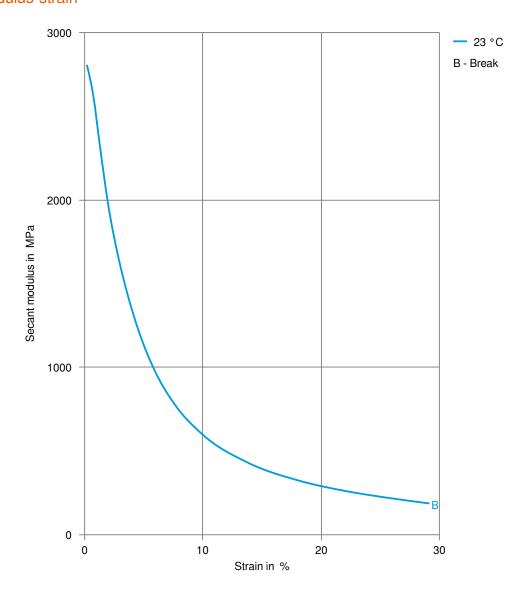
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Secant modulus-strain



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